

Symbol	Count	Hole Size	Plated	Hole Tolerance (+)	Hole Tolerance (-)
⊕	1	152.00mil (3.861mm)	NPTH	2.00mil (0.051mm)	2.00mil (0.051mm)
▽	2	118.00mil (2.997mm)	PTH	2.00mil (0.051mm)	2.00mil (0.051mm)
⊗	2	126.00mil (3.200mm)	NPTH	2.00mil (0.051mm)	2.00mil (0.051mm)
⊗	4	55.00mil (1.397mm)	PTH	3.00mil (0.076mm)	3.00mil (0.076mm)
☆	4	110.00mil (2.794mm)	PTH	2.00mil (0.051mm)	2.00mil (0.051mm)
○	5	156.00mil (3.962mm)	NPTH	2.00mil (0.051mm)	2.00mil (0.051mm)
◇	20	72.00mil (1.829mm)	PTH	3.00mil (0.076mm)	3.00mil (0.076mm)
□	81	40.00mil (1.016mm)	PTH	3.00mil (0.076mm)	3.00mil (0.076mm)
■	1266	12.00mil (0.305mm)	PTH		
1385 Total					

FABRICATION NOTES:

- 1.) MATERIAL SELECTION:
PER LATEST REVISION OF IPC-4101 (OR EQUIVALENT) UL RECOGNIZED ZPMV2 MIN.
130C FLAME CLASS V-0 OR BETTER. .062+/- .007 MATERIAL PER IPC-4101.
3 OZ. COPPER FOR EXTERNAL LAYERS. 2 OZ. COPPER FOR INTERNAL LAYERS.
SOLDERABLE SURFACES TO BE SILVER IMMERSION FINISH.
- 2.) SOLDER RESIST: THE USE OF SOLDER RESIST COATING SHALL BE IN
ACCORDANCE WITH THE REQUIREMENTS OF IPC-SM-840. ALL SOLDERABLE SURFACES
ARE TO BE FREE OF SOLDER RESIST. COLOR - GREEN.
USE LIQUID PHOTOIMAGEABLE RESIST.
- 3.) SILKSCREEN: USE WHITE NON-CONDUCTIVE INK. ALL COMPONENT AND TESTPOINT
LANDS ARE TO BE FREE OF INK.
- 4.) MANUFACTURER'S IDENTIFICATION: ADD IN ETCH OR TO SILKSCREEN.
- 5.) ELECTRICAL BARE BOARD TEST REQUIRED.
- 6.) DRILL SIZES ARE FINISHED SIZE AFTER PLATING.
- 7.) FABRICATE TO MEET EU ROHS DIRECTIVE.
- 8.) PCB MUST HAVE UL 94V-0 AND CTI RATING MARKED ON ONE SIDE.
- 9.) MAX WARP AND TWIST NOT TO EXCEED 0.010 PER LINEAR INCH.
- 10.) MIN ANNULAR RING: 0.003. MIN PLATED HOLE WALL THICKNESS 0.001.
- 11.) DIMENSIONAL TOL: XX +/- 0.010. XXX +/- 0.005.
- 12.) FABRICATE IN ACCORDANCE WITH IPC-600 OR IPC-6012 LATEST REVISION. CLASS 2.
- 13.) COPPER THEIVING OF THE SIGNAL LAYERS IS NOT ALLOWED. SPACING TO ANY EXISTING
BOARD FEATURE TO BE 0.060 MINIMUM.

PRE-PREG	TOP - SOLDERMASK 1 MIL
CORE	TOP - 3OZ COPPER 3.1 MIL
PRE-PREG	DIELECTRIC - FR4 - 8.4 MIL
	IN1 - GND PLANE - 2OZ COPPER 2.4 MIL
	DIELECTRIC - FR4 - 39 MIL
	IN2 - POWER PLANE - 2OZ COPPER 2.4 MIL
	DIELECTRIC - FR4 - 8.4 MIL
	BOTTOM - 3OZ COPPER 3.1 MIL
	BOTTOM - SOLDERMASK 1 MIL

NOMINAL REQUIRED THICKNESS 0.062 +/- 0.007